R&D on silicon detectors within the FAZIA collaboration: results and perspectives



Giovanni Casini, INFN Firenze for the SiCilia Florence branch





SiC Workshop-LNS, 7-8 april 2016

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- Physics context of FAZIA
- Improving detectors for fragment identification
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- Fighting against spoiling effects
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- A few words on Electronics
- WhatNext on Si for Heavy-ion studies
- A lesson and an expertise useful also for SiC ?

Origin of fragments in nuclear collisions

In nuclear collisions, fragments and clusters can originate together with light particles (n,p,d,t). Their production mechanisms are different, depending on the bombarding energy, the sizes of the nuclei and the impact parameter





Quartetto of Si mounted on AI (Ergal) support

BLOCKS of 16 Telescopes

Identification methods



Four-π

ventional conceptu

special features for detectors and electronics.	comments
Only A Particles are identified through Pulse Shape Analysis	Lower threshold Delicate technique
A vs. B Particles are identified through ∆E-E method	higher threshold Robust technique
A+B vs. C Particles are identified through ∆E-E method	Optimum for medium mass framents Robust technique
C Particles are identified through PSA from scintillation pulses	Restricted to Z<5 Only for very energetic

particles

Fast sampling and Pulse shape analysis (PSA)



Charge collection in Si-junctions



Electrons/holes move towards electrodes
drift time of the order of several tens ns in typical Silicon detectors Risetime differences for 12C/13C of the same energy are only 200ps: delicate technique!

BUT: on top of "external" E-field there are screening effects generated by the e-h clouds themselves: **PLASMA TIME**

Ion identification in silicon detectors: critical aspects

Structure and configuration effects

Crystalline nature of Silicon and channeling Doping inhomogeneities in Silicon bulk Mounting geometry

And for SiC?

Dynamical effects

for SiC reasonably better

Radiation damage

Electronics and digital treatment

Same issues as for Silicon

Noise sources and sampling freq limits



PSA and channeling



PSA and doping homogeneity

Good PSA needs to reduce spurious E field variations due to doping inhomogeneities

nTD bulk tech appears to be the best chance, so far

d>9 % inhomogeneities



d=1 % dishomogeneities



Typical figure of merit for good PSA: d<3%



PSA and doping homogeneity

Bardelli et al NIM A 654 2011



Keep under control channeling effects Reduce as possible doping inhomogeneities

And for PSA in SiC? Also relevant, maybe...



Charge collection in Si-junctions

PSA is expected more sensitive in reverse mounting





PSA and mounting configuration

N.LeNeindre NIM A 2013

What about ΔE -E and PSA for front injection (junction side) or for rear injection (ohmic side)?

It does matter for PSA!





S.Barlini NIM A 707 2013

- A specific study @LNS using 129Xe ions at 35MeV/u
- Damage induced in Silicons by stopped or trasmitted Xe-ions (monoenergetic)
- Used typical FAZIA 300mic and 500mic detectors, 20x20mm2
- ADC 12bit 125MSs



Automatic correction to keep applied Voltage constant!

First effect: rev. Current increase





S.Barlini NIM A 707 2013

$$\Phi_{eq} = k\Phi = k\int \phi(E) dE = \frac{\int D(E)\phi(E) dE}{D(E_n = 1 \text{ MeV})}$$

Evaluation of NIEL for 129Xe from SRIM: 1.37GeV*g/cm2 gives k=700 Xe ion are 700 time more effective to produce damage than neutrons

At least 3 orders of magnitudes to have doping inversion in n-type bulk detectors according to proton-neutron HEP test at LHC



$$D(E) = \frac{A}{N_A} NIEL(E)$$







350

300

250

200

150

100

50

0 + 0

1E+14

2E+14

Depletion Voltage (300um)

PSA and radiation damage

S.Barlini NIM A 707 2013

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NA50

3E+14

1MeV neutron eq. dose

T.Peltola NIMA 796 2015

4E+14

5E+14

6E+14

$$D(E) = \frac{A}{N_A} NIEL(E)$$





Doping inversion effect for FZ
 or CZ silicon detectors
 irradiated with neutrons



S.Barlini NIM A 707 2013

Second Effect: changes in signal evolution

A semi-expected phenomenon: change in pulse shape (ok) but in the unexpected direction: a decrease of collection times



Much less effect for Xe passing in H1, the hole where ions are transmitted



S.Barlini NIM A 707 2013

Second Effect: decrease of CCE and change of shape

For stopped ions: 15% reduction of CCE along time (fluence) For stopped ions: strong reduction of typical collection times



Much less effect for Xe passing in H1, the hole where ions are transmitted

This behaviour deserves more investigation...



S.Barlini NIM A 707 2013

Second Effect: decrease of CCE and change of shape

For stopped ions: 15% reduction of CCE along time (fluence) For stopped ions: strong reduction of typical collection times





In a typical experiment....

Case of **Xe** ions For a limit of 1% Charge collection and risetime variation we get safe PSA life-limits:

Fluence of 10⁷ /cm2 for stopped ions

Fluence of 3*10⁸ /cm2 for punching-through ions

For 200Hz rate on Si pads at 1deg (2x2cm2) this is around 2.5 days for stopped heavy ions and 75 days for trasmission ions.

Considering a square Z dependence (*) one can deduce that for lighter ions these limits become

(*) not investigated

Kr 5.6 days for stopped heavy ions and 170 days for trasmission ions.

O 114 days for stopped heavy ions and 3400 days for trasmission ions.

Radiation damage remains an issue

RESULTS: Towards the limits of ΔE -E



Isotopic separation achieved up to Z=23-25 Charge separation up to Z=54 (it's not a limit)

Results from Phase1

Strong improvement of PSA

IONS STOPPING IN A SINGLE LAYER



For path in the Silicon detector lower than 30 μ m (for a C) to 100 μ m (for a Xe), no discrimination is possible using PSA.



PSA

Charge separation is obtained up to Xenon (Z=54)

Mass separation is more critical; up to Z=14 in best detector-electronics conditions

Reverse mounting needed

IMAX is better that QriseTime as a shape parameter

Giovanni Casini INFN Florence



NOTE: So far most of these Silicon 20x20mm2 pads were produced by FBK starting from special 4inch nTD wafers from TOPSIL

The basic FAZIA Block





telescopes

FEE boards, 6x8 channels

HV stage, Block Card, electro-optical coupling

BLOCK: is the stand-alone FAZIA Module **1**6 Si-Si-Telescopes

 8 FEE Cards wit 48 lines of preamplifiers, ADC and

FPGA

Power Generators and regulators. Pulser generation and control







PSA in Silicon over a 'large' scale

The good performance are confirmed in recent (2015) experiments, too



Present identification quality



(adapted from J.Frankland, Spiral2 week, 2014)

The basic FAZIA Block: not only detectors...

Block

Charge and current l.n. Preamps; 48 channels on 8 FEE cards. Each FEE contains with 6 channels

Cooling Plate

Block Frame

Head of



Detection FEE Cards Card Kapton, Wires Stage 1 (300 µm silicon detector): Charge: 250 Ms/s 14 bit (250MeV full scale) Charge: 100 Ms/s 14 bit (4 GeV full scale) Current: 250 Ms/s 14bit **IPN (Orsay)** Stage 2 (500 µm silicon detector): Charge: 100 Ms/s 14 bit (4 GeV full scale) Current: 250 Ms/s 14bit Stage 3 (10 cm CsI(Tl) + photo-diode): Charge: 100 Ms/s 14 bit (4 GeV silicon-equivalent full scale)

Powerful electronics

High Power, cooling, large data Bandwidth: all on a few cables !



MAJOR CONTRIBUTIONS: IPN (Orsay), INFN Naples and INFN Florence

Giovanni Casini INFN Florence

Ion identification in silicon detectors: new efforts

Lower identification thresholds

Very thin (large area) detectors for DE-E, but PSA? Combine PSA with TOF? Timing issue... (see Lu et al.)

Improve identification quality

Lowering bias voltage (uncomplete depletion)

More radiation resistent chips

SiC promise... as we're discussing

Long term plans >2020: FAZIA (12 blocks) @SPES (and Spiral2)

FAZIA very good for Fermi energy domain but what about n-rich ISOL Beams?



very thin Epitaxial detectors

21µm

thick



Z-identification with thresholds as low as 1.1MeV for protons and 2MeV/u for Mn ions.

20mm



Use very thin and "large" square FAZIA-custom detectors as a first Silicon stage.

- Recovering ∆E-E method
- Encouraging results



Partially depleted Silicon detectors



Pasquali et al Eur. Phys. J. A (2014) 50: 86

- What if the E field is decreased within the bulk
- Larger PSA sensitivity?
- Spoiled Energy resolution?
- Thresholds?

Kr+Sn,Au at 35 MeV/u **FAZIA** telescopes

Collection Times strongly increase from V=105Volt300ns to 13000ns



ns

V=290Volt





ns

Partially depleted Silicon detectors



 ΔE -E technique and Energy

Rather surprinsingly

- Energy calibration only slightly changes from 290 to 105Volt
- CCE remains high (only 2% deficit for energetic ions)
- CCE is still high (8% deficit) for ions stopping in the E=0 region

Isotopic separation holds FoM don't change

Energy measurement is preserved (see Table, right) provided that a long shaping time is used

Isotopes	Applied voltage (V)				
horopoo	105	130	200	235	290
⁶ Li- ⁷ Li	1.51(9)	1.5(2)	1.4(1)	1.5(1)	1.5(1)
${}^{11}\text{B}{}^{-12}\text{B}$	1.52(4)	1.50(6)	1.54(6)	1.43(6)	1.42(5)
${}^{12}\text{C-}{}^{13}\text{C}$	1.50(5)	1.44(5)	1.50(6)	1.50(5)	1.51(6)
$^{21}\mathrm{Ne}\text{-}^{22}\mathrm{Ne}$	1.18(9)	1.21(6)	1.20(8)	1.18(3)	1.19(8)

Partially depleted Silicon detectors



Maximum of the current signal



PSA is strongly affected

Rather surprinsingly

- Identification quality changes from 290 to 105Volt
- Isotopes are better separated at low voltages
- Charge separation is obtained at higher thresholds for undepleted operation



Conclusions

Many aspects related to an optimum use of Si detectors for heavy ion spectroscopy have been evidenced during the FAZIA activity

Parameters to be kept under control for PSA and DE-E

Orientation of processing and mounting Homogeneity of the doping Metalization of surfaces Radiation Damage

Other subjects

Going to thin detectors Underbiasing and PSA Charge collction in Zero Field regions Best filters (analysis of samples) Timing

This is an expertise than can be useful for SiC developments in the HIC field

